MATERIALS FOR ADVANCED ELECTRONICS

Electronics are being woven more and more deeply into the fabric of everyday life. The fierce pace of development and competition in this market drives a constant demand for thinner, lighter, more energy-efficient and wireless devices. To help address these challenges, manufacturers seek to make products that are costeffective to produce and can meet consumers' preferences for style, ease of use and sustainability.

SABIC's materials can be the foundation for the next generation of electronic devices. Use the links below to read more about each of the material solutions to support the development of advanced electronics.

MINIATURIZATION

THERMOCOMP™ compounds – laser direct structuring of integrated 3D molded interconnected device (MID) with fine pitch printed circuits to support miniaturization.

HEAT MANAGEMENT

KONDUIT[™] compounds – thermally conductive material to cool down sensitive electronics such as sensors and LED's in order to extend their lifetime and reduce maintenance.

STRUCTURAL DESIGN

THERMOCOMP™ HMD compounds – thin wall design through low halogen flame retardancy down to V0 0.6mm and tight dimensions due to specific glass fiber contents from 10% to 50%.

EMI SHIELDING

FARADEX[™] compounds – reliable electromagnetic interference shielding (EMI) with no need for secondary operation steps for the electromagnetic compatibility of your electronic device.

DIFLECTRIC PROPERTIES

THERMOCOMP™ compounds – individual antenna design with low signal absorption and tailor made Dielectric constant to support innovative antenna designs and miniaturization through high D_k and low D_f material properties.

ELECTRICAL CONDUCTIVITY

STAT-KON™ compounds – electrical conductive materials to prevent static-electricity build up and to reduce risks of electro-static discharge at sensitive electronic devices.









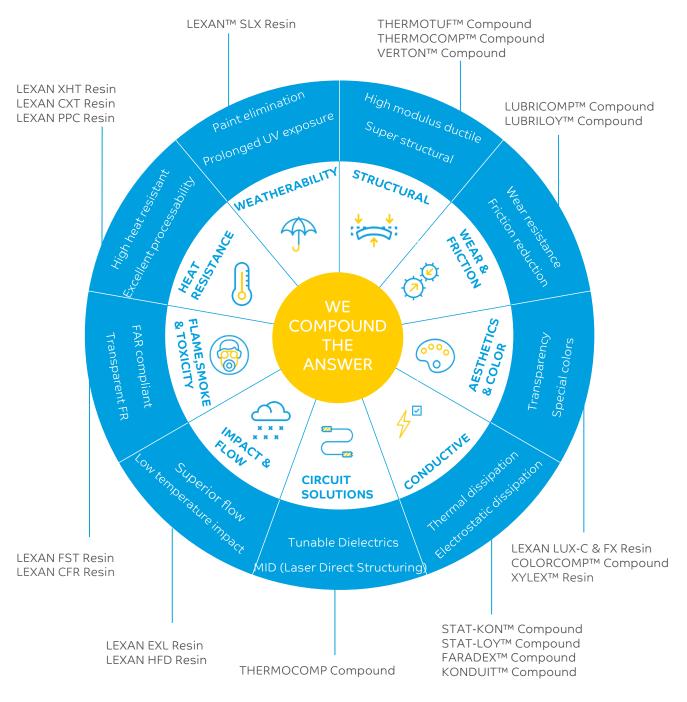






LNP™ COMPOUNDS & LEXAN™ COPOLYMER RESINS

Over 70 years of innovation in thermoplastic compounding enables SABIC's specialty compounds to offer extensive materials with a broad portfolio.



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